

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AIKO MIZUSAWA	07/04/2008
OSAMU OKADA	07/04/2008
TAKESHI WAKABAYASHI	07/04/2008
ICHIRO MIHARA	07/04/2008
RECEIVING PARTY DATA	
Name:	CASIO COMPUTER CO., LTD.
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State/Country:	JAPAN
Postal Code:	151-8543
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14750665
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NAME OF SUBMITTER:	ALLYSON PLANDERS
SIGNATURE:	/Allyson Planders/
DATE SIGNED:	06/25/2015
Total Attachments: 2	
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ASSIGNMENT

C2537P0701L
(07S1326-1I)

In consideration of value received, I, having a mailing address at c/o Intellectual Property Department, Casio Computer Co., Ltd., Hamura R&D Center, 2-1, Sakae-cho 3-chome, Hamura-shi, Tokyo 205-8555, Japan, and a residence as stated below next to my name, the sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are listed below) of an invention described in an application for United States patent entitled:

SEMICONDUCTOR DEVICE HAVING LOW DIELECTRIC INSULATING FILM AND MANUFACTURING METHOD OF THE SAME

said application having been filed on June 4, 2008
and assigned Application No. 12/156,822 ;
sell and assign to
CASIO COMPUTER CO., LTD.
a corporation of Japan, having a business address at
6-2, Hon-machi 1-chome, Shibuya-ku, Tokyo 151-8543, Japan

its successors, assigns or nominees, hereinafter referred to as "Assignee", my entire right, title and interest in and to said invention as disclosed, shown and described in said application for United States patent : (check one)

- ☒ [X] executed concurrently herewith;
☐ [] executed separately herefrom;

and in and to all applications for patent and patents for said invention including all divisions, reissues, continuations, substitutions and extensions thereof and all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property, including rights of priority, resulting from the filing of any of said applications; and I authorize and request any official whose duty is to issue patents, to issue any patent on said invention or resulting therefrom to said Assignee, and I agree that on request and without further consideration, but at the expense of said Assignee, I will communicate to said Assignee or its representatives all facts known to me respecting said invention and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue or other applications, make all rightful oaths and declarations, and generally do everything possible to aid said Assignee to obtain and enforce proper patent protection for said invention in all countries.

I hereby grant the following law firm the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the Rules of the U.S. Patent and Trademark Office for recordation of this document.

Frishauf, Holtz, Goodman & Chick, P.C., 220 Fifth Avenue - 16th Floor New York,
NY 10001-7708

PATENT
REEL: 021372 FRAME: 0616

PATENT
REEL: 035908 FRAME: 0399

ASSIGNMENT

C2537P0701L

(07S1326-1I)

<u>Inventor: (Signature)</u>	<u>Date</u>	<u>Residence</u>
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RECORDED: 08/12/2008

PATENT
REEL: 021372 FRAME: 0617

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REEL: 035908 FRAME: 0400